



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ042N06NS		<b>Issued</b>		3. June 2015		
<b>MA#</b>		MA000959888						
<b>Package</b>		PG-TSDSON-8-26		<b>Weight*</b>		36.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	1.71	1.71	17110	17110
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		268	
	non noble metal	iron	7439-89-6	0.197	0.54		5351	
wire	non noble metal	copper	7440-50-8	7.988	21.73	22.31	217271	222957
	noble metal	gold	7440-57-5	0.027	0.07	0.07	725	725
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1002	
	plastics	epoxy resin	-	1.897	5.16		51604	
	inorganic material	silicondioxide	60676-86-0	16.486	44.83	50.09	448405	501011
leadfinish	non noble metal	tin	7440-31-5	0.400	1.09	1.09	10885	10885
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	553	553
solder	noble metal	silver	7440-22-4	0.023	0.06		637	
	non noble metal	tin	7440-31-5	0.019	0.05		510	
	non noble metal	lead	7439-92-1	0.895	2.43	2.54	24331	25478
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2556	
	non noble metal	copper	7440-50-8	3.816	10.38	10.65	103787	106503
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		34	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.101	0.28		2755	
	non noble metal	copper	7440-50-8	4.112	11.19	11.48	111851	114778
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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